Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP ENVY x360 Convertible PC 15m

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack;RTC</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>LED</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Phillips screwdriver (for 12 PCS on bottom case)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #2 Phillips screwdriver (for 9 PCS on motherboard)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #3 Phillips screwdriver (for 2 PCS on HDD Bracket &amp; 4 PCS on Battery)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #4 Phillips screwdriver (for 10 PCS on base side hinge bracket)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #5 Use jig disassembly Lcd Bezel with Lcd cover</td>
<td>Pick thickness 0.3~0.4mm</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove rear side rubber foot refer figure 1
2. Release 7pcs Phillips screw from bottom case refer figure 2
3. Two hand together dissemble bottom case from arrow side refer figure 3
4. Release 7pcs Phillips screw from Battery refer figure 4
5. Dissemble: DC-in cable, WLAN cable, CCD cable, EDP cable, SPK cable, SD FFC, HDD FFC, KB BL FPC, KB FPC, TP FFC refer figure 5
6. Release 14pcs Phillips screw from PCB, Next Teardown Mainboard and SD board refer figure 6
7. Release 3pcs Phillips screw from left side hinge bracket refer figure 7
8. Release 3pcs Phillips screw from right side hinge bracket refer figure 8
9. Dissemble LCD module initial step pick insert gap between LCD Cover and LCD Bezel refer figure 9
10. Release 6pcs Phillips screw from right & left hinge Bracket refer figure 10

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove rear side rubber foot

*Use Knife*

*Figure 1*

1. Two hand together disassemble bottom case from arrow side

*Figure 3*

1. Release 7pcs Phillips screw from bottom case

*Use Phillips screwdriver*

*Figure 2*

1. Release 7pcs Phillips screw from Battery

*Use Phillips screwdriver*

*Figure 4*
1. Disassemble: DC-in cable, WLAN cable, CCD cable, EDP cable, SPK cable, SD FFC, HDD FFC, KB BL FPC, KB FPC, TP FFC

Figure 5

1. Release 3pcs Phillips screw from left side hinge bracket

Use Phillips screwdriver
Figure 7

1. Disassemble LCD module initial step pick insert gap between LCD Cover and LCD Bezel

Pick thickness 0.3~0.4mm
Figure 9

1. Release 14pcs Phillips screw from PCB
2. Teardown Mainboard and SD board

Use Phillips screwdriver
Figure 6

1. Release 3pcs Phillips screw from right side hinge bracket

Use Phillips screwdriver
Figure 8

1. Release 6pcs Phillips screw from right & left hinge Bracket

Use Phillips screwdriver
Figure 10

PSG instructions for this template are available at EL-MF877-01